

Title (en)

Transparent electromagnetic radiation shield material and method of producing the same

Title (de)

Durchsichtiges Abschirmmaterial gegen elektromagnetische Bestrahlung und Verfahren zu dessen Herstellung

Title (fr)

Matériau transparent de blindage contre les radiations électromagnétiques et sa méthode de fabrication

Publication

EP 1109434 A3 20020724 (EN)

Application

EP 00311097 A 20001213

Priority

JP 37670099 A 19991217

Abstract (en)

[origin: EP1109434A2] A transparent electromagnetic radiation shield material includes a transparent base material, a hydrophobic transparent resin coating containing reduced metal particles laminated on the base material, and a mesh-like electroless plating layer laminated on the coating to form in the coating under the plating layer a blackened portion of mesh-like pattern identical to and aligned with that of the plating layer. A method of producing a transparent electromagnetic radiation shield material includes a step of laminating a hydrophobic transparent resin coating containing reduced metal particles on a transparent base material, a step of treating the coating with a nonaqueous electroless plating solution, a step of forming an electroless plating layer on the entire surface of the coating while simultaneously blackening the coating, a step of forming a mesh-like resist layer on the electroless plating layer, a step of removing portions of the electroless plating layer where no resist is present and blackened portions of the coating thereunder, and a step of optionally peeling off the resist layer.

IPC 1-7

H05K 9/00

IPC 8 full level

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CPC (source: EP)

H05K 9/0096 (2013.01)

Citation (search report)

- [A] EP 0817557 A2 19980107 - NISSHIN SPINNING [JP]
- [A] PATENT ABSTRACTS OF JAPAN vol. 013, no. 254 (E - 772) 13 June 1989 (1989-06-13)
- [AD] PATENT ABSTRACTS OF JAPAN vol. 017, no. 286 (M - 1422) 2 June 1993 (1993-06-02)
- [DA] PATENT ABSTRACTS OF JAPAN vol. 1998, no. 08 30 June 1998 (1998-06-30)

Cited by

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